# HT73xx-7 30V, 250mA TinyPower™ LDO with Protections

#### **Features**

- Low power consumption
- · Low voltage drop
- · Low temperature coefficient
- High input voltage up to 30V
- Output voltage accuracy: tolerance ±2%
- · Over current protection
- Over temperature protection
- · Chip enable/disable function
- Package types: 3-pin SOT89 and 8-pin SOP-EP

### **Applications**

- · Battery-powered equipment
- · Communication equipment
- · Audio/Video equipment

### **General Description**

The HT73xx-7 is a low power high voltage series of regulators implemented in CMOS technology which has the advantages of low voltage drop and low quiescent current. They allow input voltages as high as 30V and are available with several fixed output voltages ranging from 2.1V to 5.0V.

When the CE input is low, a fast discharge path pulls the output voltage low via an internal pull-down resistor. An internal over-current protection circuit prevents the device from damage even if the output is shorted to ground. An over-temperature protection circuit ensures the device junction temperature will not exceed a temperature of 150°C.

### **Selection Table**

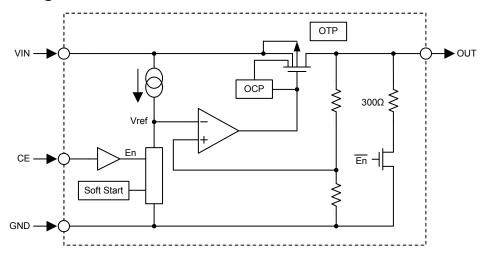
Part No.	Output Voltage	Packages	Markings
HT7321-7	2.1V		
HT7323-7	2.3V		
HT7325-7	2.5V		
HT7327-7	2.7V	SOT89 73xx-7 (for SOT89	
HT7330-7	3.0V		73xx-7 (for SOT89)
HT7333-7	3.3V	8SOP-EP	HT73xx-7 (for 8SOP-EP)
HT7336-7	3.6V		
HT7340-7	4.0V		
HT7344-7	4.4V		
HT7350-7	5.0V		

Note: "xx" stands for output voltages.

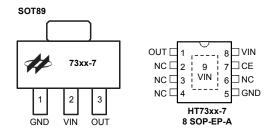
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# **Block Diagram**



# **Pin Assignment**



# **Pin Descriptions**

Pin No.		Pin Name	Pin Description	
SOT89	8SOP-EP	Pili Naille	Pili Description	
1	5	GND	Ground pin	
2	8, 9	VIN	Input pin	
3	1	OUT	Output pin	
_	7	CE	Chip enable pin, high enable	
_	2, 3, 4, 6	NC	No connection	

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## **Absolute Maximum Ratings**

Parameter	Value	Unit	
V <sub>IN</sub>	-0.3 to +33	V	
Vce	-0.3 to (V <sub>IN</sub> +0.3)	V	
Operating Temperature Range, Ta		-40 to +85	°C
Maximum Junction Temperature, T <sub>J(MAX)</sub>	+150	°C	
Storage Temperature Range	-65 to +165	°C	
Lunction to Ambient Thermal Desistance O	SOT89	200	°C/W
Junction-to-Ambient Thermal Resistance, θ <sub>JA</sub>	8SOP-EP	125	°C/W
Dawer Dissination D	SOT89	0.50	W
Power Dissipation, P <sub>D</sub>	8SOP-EP	0.80	W

Note: P<sub>D</sub> is measured at Ta=25°C.

# **Recommended Operating Range**

Parameter	Value	Unit
V <sub>IN</sub>	V <sub>OUT</sub> +2 to 30	V
Vce	0 to V <sub>IN</sub>	V

### **Electrical Characteristics**

 $V_{\text{IN}}\text{=}V_{\text{OUT}}\text{+}2V,\,V_{\text{CE}}\text{=}V_{\text{IN}},\,Ta\text{=}25^{\circ}C$  and  $C_{\text{IN}}\text{=}C_{\text{OUT}}\text{=}10\mu\text{F},\,unless otherwise specified}$ 

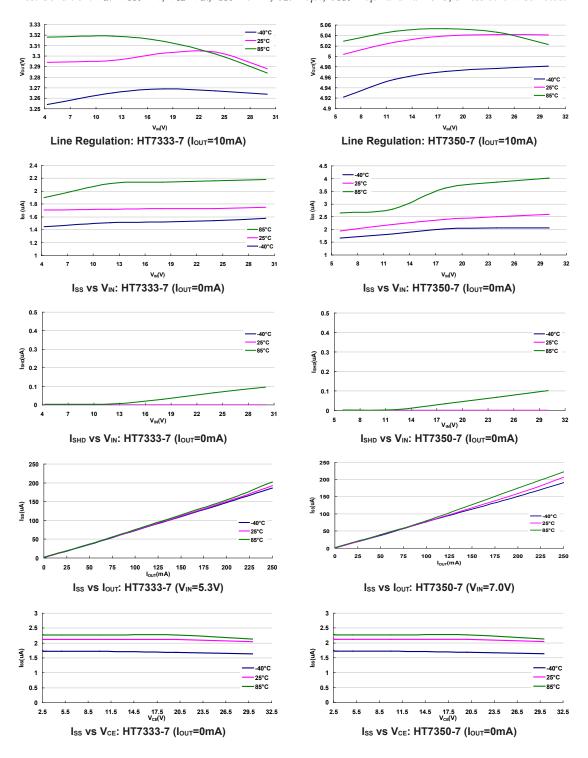
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Vin	Input Voltage	_	_	_	30	V
V <sub>оит</sub>	Output Voltage Range	_	2.1	_	5.0	V
Vo	Output Voltage Accuracy	I <sub>OUT</sub> =10mA	-2	_	2	%
Гоит	Output Current	_	250	_	_	mA
ΔV <sub>OUT</sub>	Load Regulation	1mA ≤ I <sub>OUT</sub> ≤ 100mA	_	45	90	mV
V	Drangut Valtage	I <sub>OUT</sub> =1mA, V <sub>OUT</sub> Change=2% (Note)	_	6	15	mV
$V_{DIF}$	Dropout Voltage	I <sub>OUT</sub> =30mA, V <sub>OUT</sub> Change=2% (Note)	_	120	300	mV
I <sub>SS1</sub>	Outropy of Comment	I <sub>OUT</sub> =0mA	_	2.5	4.0	μA
I <sub>SS2</sub>	Quiescent Current	V <sub>CE</sub> =2.0V, V <sub>IN</sub> =30V, I <sub>OUT</sub> =0mA	_	3.0	5.0	μA
I <sub>SHD</sub>	Shutdown Current	V <sub>CE</sub> =0V	_	0.1	0.5	μA
$\frac{\Delta V_{\text{OUT}}}{\Delta V_{\text{IN}} \times \Delta V_{\text{OUT}}}$	Line Regulation	$(V_{OUT}+1V) \le V_{IN} \le 30V, I_{OUT}=1mA$	_	0.1	0.2	%/V
$\frac{\Delta V_{\text{OUT}}}{\Delta T_{\text{a}} \times \Delta V_{\text{OUT}}}$	Temperature Coefficient	I <sub>оит</sub> =40mA, -40°С < Та < 85°С	_	±100	_	ppm/°C
I <sub>SHORT</sub>	Output Short Current	V <sub>IN</sub> =12V, force V <sub>OUT</sub> =0V	_	250	_	mA
T <sub>SHD</sub>	Shutdown Temperature	_	_	150	_	°C
T <sub>REC</sub>	Recovery Temperature	_	_	25	_	°C
V <sub>IH</sub>	Enable High Threshold	CE pin, V <sub>OUT</sub> +1V ≤ V <sub>IN</sub> ≤ 30V	2.0	_	_	V
V <sub>IL</sub>	Enable Low Threshold	CE pin, V <sub>OUT</sub> +1V ≤ V <sub>IN</sub> ≤ 30V	_	_	0.6	V
R <sub>DIS</sub>	Discharge Resistor	CE=0V, measure at V <sub>OUT</sub>	_	300	_	Ω

Note: The dropout voltage is defined as the input voltage minus the output voltage that produces a 2% change in the output voltage from the value at  $V_{IN}=V_{OUT}+2V$  with a fixed load.

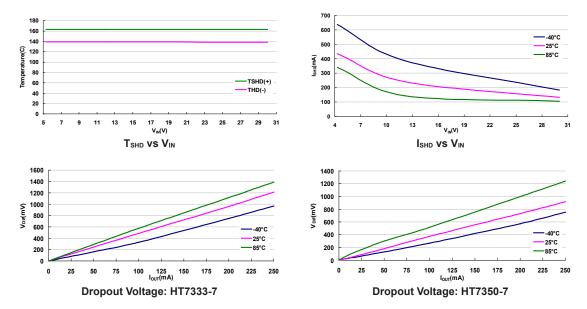
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# **Typical Performance Characteristic**

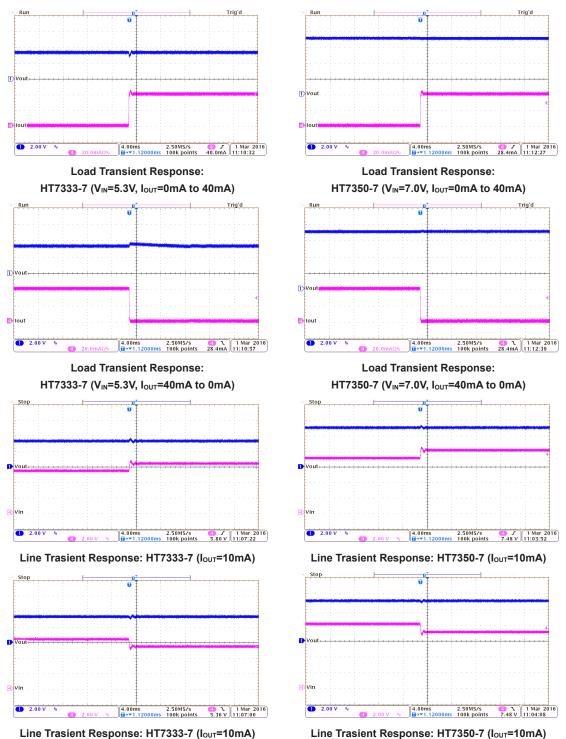




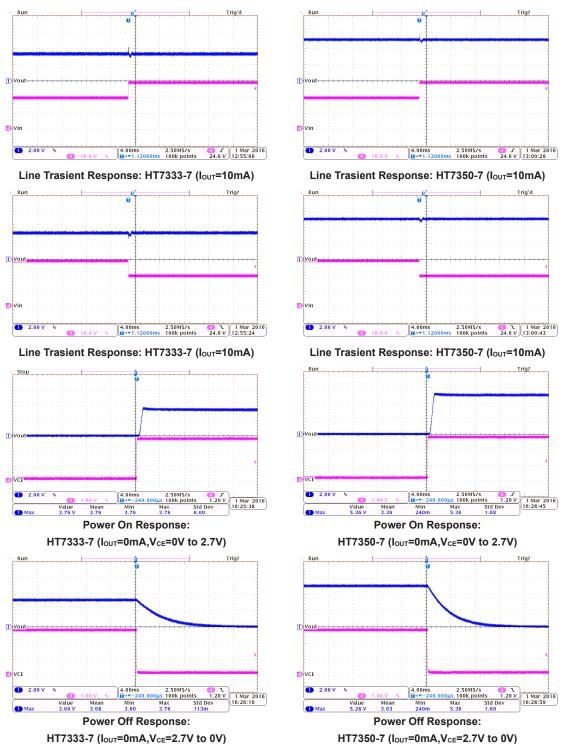


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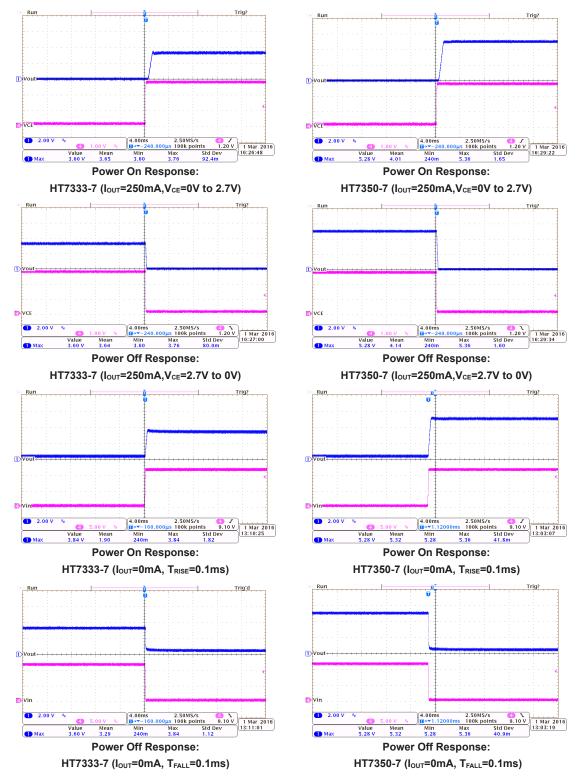




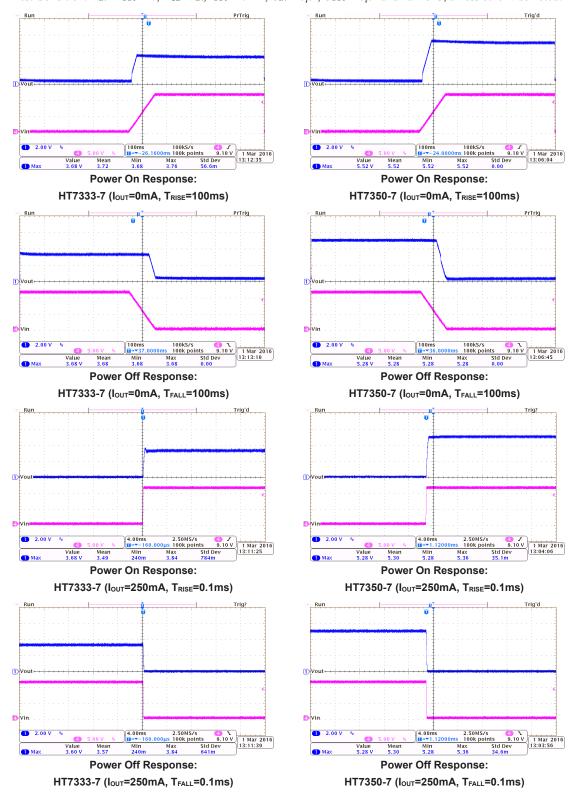




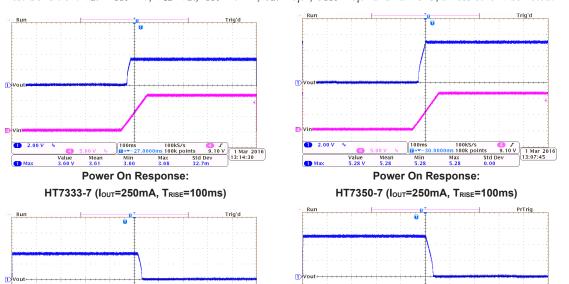












Power Off Response:

HT7333-7 (I<sub>OUT</sub>=250mA, T<sub>FALL</sub>=100ms)

Power Off Response: HT7350-7 ( $I_{OUT}$ =250mA,  $T_{FALL}$ =100ms)



### **Application Information**

When using the HT73xx-7 regulators, it is important that the following application points are noted if correct operation is to be achieved.

#### **External Circuit**

It is important that external capacitors are connected to both the input and output pins. For the input pin suitable bypass capacitors as shown in the application circuits should be connected especially in situations where a battery power source is used which may have a higher impedance. For the output pin, a suitable capacitor should also be connected especially in situations where the load is of a transient nature, in which case larger capacitor values should be selected to limit any output transient voltages.

#### **Thermal Considerations**

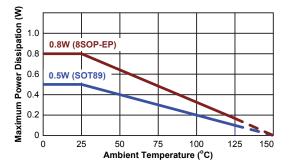
The maximum power dissipation depends on the thermal resistance of the package, the PCB layout, the rate of the surrounding airflow and the difference between the junction and ambient temperature. The maximum power dissipation can be calculated using the following formula:

$$P_{D(MAX)} = (T_{J(MAX)} - T_a) / \theta_{JA}$$

where  $T_{J(MAX)}$  is the maximum junction temperature,  $T_a$  is the ambient temperature and  $\theta_{JA}$  is the junction-to-ambient thermal resistance of the IC package in degrees per watt. The following table shows the  $\theta_{JA}$  values for various package types.

Package	θ <sub>JA</sub> value °C/W
SOT89	200°C/W
8SOP-EP	125°C/W

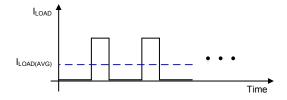
For maximum operating rating conditions, the maximum junction temperature is 150°C. However, it is recommended that the maximum junction temperature does not exceed 125°C during normal operation to maintain an adequate margin for device reliability. The derating curves of different packages for maximum power dissipation are as follows:



#### **Power Dissipation Calculation**

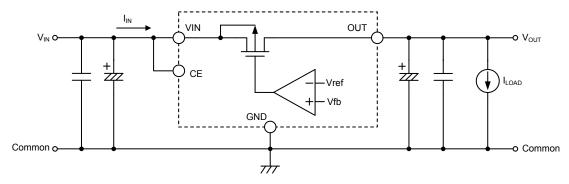
In order to keep the device within its operating limits and to maintain a regulated output voltage, the power dissipation of the device, given by  $P_D$ , must not exceed the Maximum Power Dissipation, given by  $P_{D(MAX)}$ . Therefore  $P_D \leq P_{D(MAX)}$ . From the diagram it can be seen that almost all of this power is generated across the pass transistor which is acting like a variable resistor in series with the load to keep the output voltage constant. This generated power which will appear as heat, must never allow the device to exceed its maximum junction temperature.

In practical applications the regulator may be called upon to provide both steady state and transient currents due to the transient nature of the load. Although the device may be working well within its limits with its steady state current, care must be taken with transient loads which may cause the current to rise close to its maximum current value. Care must be taken with transient loads and currents as this will result in device junction temperature rises which must not exceed the maximum junction temperature. With both steady state and transient currents, the important current to consider is the average or more precisely the RMS current which is the value of current that will appear as heat generated in the device. The following diagram shows how the average current relates to the transient currents.



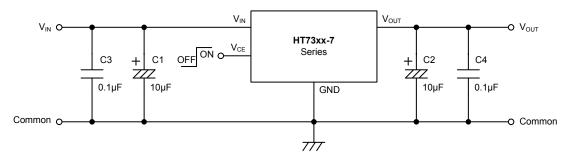


As the quiescent current of the device is very small it can generally be ignored and as a result the input current can be assumed to be equal to the output current. Therefore the power dissipation of the device,  $P_D$ , can be calculated as the voltage drop across the input and output multiplied by the current, given by the equation,  $P_D = (V_{IN} - V_{OUT}) \times I_{IN}$ . As the input current is also equal to the load current the power dissipation  $P_D = (V_{IN} - V_{OUT}) \times I_{LOAD}$ . However, with transient load currents,  $P_D = (V_{IN} - V_{OUT}) \times I_{LOAD(AVG)}$  as shown in the figure.

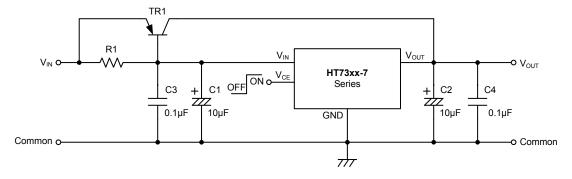


# **Application Circuits**

#### **Basic Circuits**



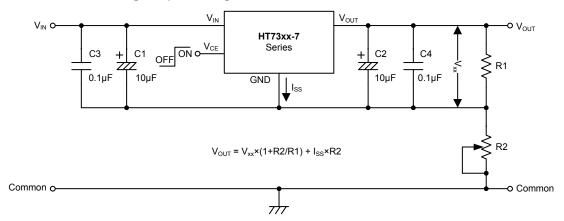
### **High Output Current Positive Voltage Regulator**



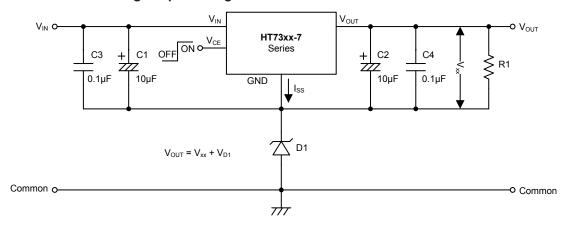
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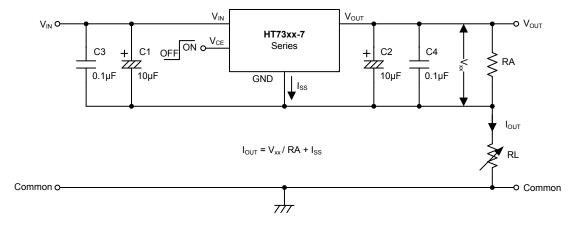
### **Circuit for Increasing Output Voltage**



### **Circuit for Increasing Output Voltage**

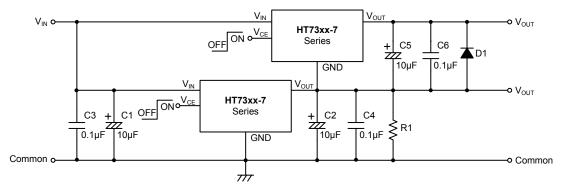


### **Constant Current Regulator**





# **Dual Supply**





## **Package Information**

Note that the package information provided here is for consultation purposes only. As this information may be updated at regular intervals users are reminded to consult the <u>Holtek website</u> for the latest version of the <u>Package/Carton Information</u>.

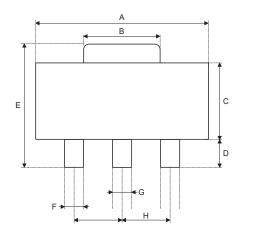
Additional supplementary information with regard to packaging is listed below. Click on the relevant section to be transferred to the relevant website page.

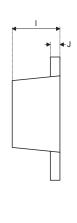
- Package Information (include Outline Dimensions, Product Tape and Reel Specifications)
- The Operation Instruction of Packing Materials
- Carton information

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# 3-pin SOT89 Outline Dimensions





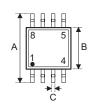
Cumbal	Dimensions in inch			
Symbol	Min.	Nom.	Max.	
A	0.173	_	0.185	
В	0.053	_	0.072	
С	0.090	_	0.106	
D	0.031	_	0.047	
E	0.155	_	0.173	
F	0.014	_	0.019	
G	0.017	_	0.022	
Н	_	0.059 BSC	_	
1	0.055	_	0.063	
J	0.014	_	0.017	

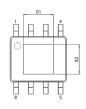
Symbol	Dimensions in mm			
Зушьог	Min.	Nom.	Max.	
A	4.40	_	4.70	
В	1.35	_	1.83	
С	2.29	_	2.70	
D	0.80	_	1.20	
E	3.94	_	4.40	
F	0.36	_	0.48	
G	0.44	_	0.56	
Н	_	1.50 BSC	_	
I	1.40	_	1.60	
J	0.35	_	0.44	

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# 8-pin SOP-EP Outline Dimensions









Cumbal		Dimensions in inch			
Symbol	Min.	Nom.	Max.		
A	_	0.236 BSC	_		
В	_	0.154 BSC	_		
С	0.012	_	0.020		
C'	_	0.193 BSC	_		
D	_	_	0.069		
D1	0.059	_	_		
E	_	0.050 BSC	_		
E2	0.039	_	_		
F	0.004	_	0.010		
G	0.016	_	0.050		
Н	0.004	_	0.010		
α	0°	_	8°		

Cumbal	Dimensions in mm			
Symbol	Min.	Nom.	Max.	
A	_	6.00 BSC	_	
В	_	3.90 BSC	_	
С	0.31	_	0.51	
C'	_	4.90 BSC	_	
D	_	_	1.75	
D1	1.50	_	_	
E	_	1.27 BSC	_	
E2	1.00	_	_	
F	0.10	_	0.25	
G	0.40	_	1.27	
Н	0.10	_	0.25	
α	0°	_	8°	



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